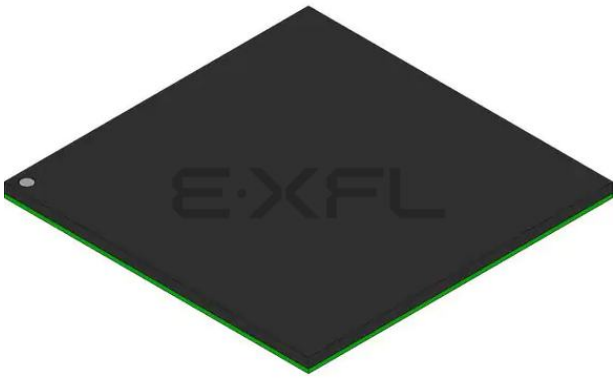


Welcome to E-XFL.COM

Understanding Embedded - Microprocessors

Embedded microprocessors are specialized computing chips designed to perform specific tasks within an embedded system. Unlike general-purpose microprocessors found in personal computers, embedded microprocessors are tailored for dedicated functions within larger systems, offering optimized performance, efficiency, and reliability. These microprocessors are integral to the operation of countless electronic devices, providing the computational power necessary for controlling processes, handling data, and managing communications.

Applications of Embedded - Microprocessors

Embedded microprocessors are utilized across a broad spectrum of applications, making them indispensable in

Details	
Product Status	Active
Core Processor	ARM920T
Number of Cores/Bus Width	1 Core, 32-Bit
Speed	150MHz
Co-Processors/DSP	-
RAM Controllers	SDRAM
Graphics Acceleration	No
Display & Interface Controllers	LCD
Ethernet	-
SATA	-
USB	USB 1.x (1)
Voltage - I/O	1.8V, 3.0V
Operating Temperature	0°C ~ 70°C (TA)
Security Features	-
Package / Case	256-LFBGA
Supplier Device Package	256-PBGA (14x14)
Purchase URL	https://www.e-xfl.com/pro/item?MUrl=&PartUrl=mc9328mxlvm15

- Video Port
- General-Purpose I/O (GPIO) Ports
- Bootstrap Mode
- Multimedia Accelerator (MMA)
- Power Management Features
- Operating Voltage Range: 1.7 V to 1.9 V core, 1.7 V to 3.3 V I/O
- 256-pin MAPBGA Package
- 225-contact MAPBGA Package

1.2 Target Applications

The i.MXL processor is targeted for advanced information appliances, smart phones, Web browsers, digital MP3 audio players, handheld computers, and messaging applications.

1.3 Ordering Information

Table 1 provides ordering information.

Table 1. i.MXL Ordering Information

Package Type	Frequency	Temperature	Solderball Type	Order Number
256-lead MAPBGA	200 MHz	0°C to 70°C	Pb-free	MC9328MXLVM20(R2)
		-30°C to 70°C	Pb-free	MC9328MXLDVM20(R2)
	150 MHz	0°C to 70°C	Pb-free	MC9328MXLVM15(R2)
		-30°C to 70°C	Pb-free	MC9328MXLDVM15(R2)
		-40°C to 85°C	Pb-free	MC9328MXLCVM15(R2)
225-lead MAPBGA	200 MHz	0°C to 70°C	Pb-free	MC9328MXLVP20(R2)
		-30°C to 70°C	Pb-free	MC9328MXLDVP20(R2)
	150 MHz	0°C to 70°C	Pb-free	MC9328MXLVP15(R2)
		-30°C to 70°C	Pb-free	MC9328MXLDVP15(R2)
		-40°C to 85°C	Pb-free	MC9328MXLCVP15(R2)

1.4 Conventions

This document uses the following conventions:

- $\overline{\text{OVERBAR}}$ is used to indicate a signal that is active when pulled low: for example, $\overline{\text{RESET}}$.
- *Logic level one* is a voltage that corresponds to Boolean true (1) state.
- *Logic level zero* is a voltage that corresponds to Boolean false (0) state.
- To *set* a bit or bits means to establish logic level one.
- To *clear* a bit or bits means to establish logic level zero.
- A *signal* is an electronic construct whose state conveys or changes in state convey information.

Table 3. MC9328MXLMC9328MXS Signal Multiplexing Scheme (Continued)

I/O Supply Voltage	225 BGA Ball	256 BGA Ball	Primary			Alternate		GPIO		AIN	BIN	AOUT	Default
			Signal	Dir	Pull-Up	Signal	Dir	Mux	Pull-Up				
NVDD1	F1	E1	A20	O		ETMPIPESTAT0	O	PA28	69K				A20
NVDD1	F4	F2	D27	I/O	69K								
NVDD1	F2	F4	A19	O		ETMTRACEPKT3	O	PA27	69K				A19
NVDD1	G3	E4	D26	I/O	69K								
NVDD1	G2	F1	A18	O		ETMTRACEPKT2	O	PA26	69K				A18
NVDD1	G4	F3	D25	I/O	69K								
NVDD1	G1	G2	A17	O		ETMTRACEPKT1	O	PA25	69K				A17
NVDD1	H4	G3	D24	I/O	69K								
NVDD1	H2	F5	A16	O		ETMTRACEPKT0	O	PA24	69K				A16
NVDD1	H3	G4	D23	I/O	69K								
NVDD1	H1	G1	A15	O									
NVDD1	H5	H2	D22	I/O	69K								
NVDD1	J1	H3	A14	O									
NVDD1	J3	G5	D21	I/O	69K								
NVDD1	K1	H1	A13	O									
NVDD1	J4	H4	D20	I/O	69K								
NVDD1	J2	J1	A12	O									
NVDD1	K4	J4	D19	I/O	69K								
NVDD1	K2	J2	A11	O									
NVDD1	L4	J3	D18	I/O	69K								
NVDD1	L1	K1	A10	O									
NVDD1	L3	K4	D17	I/O	69K								
NVDD1	L2	K3	A9	O									
NVDD1	M1	K2	D16	I/O	69K								
NVDD1	N1	L1	A8	O									
NVDD1	M2	L4	D15	I/O	69K								
NVDD1	N2	L2	A7	O									
NVDD1	P1	L5	D14	I/O	69K								
NVDD1	R1	M4	A6	O									
NVDD1	M3	L3	D13	I/O	69K								
NVDD1	P2	M1	A5	O									
NVDD1	N3	M2	D12	I/O	69K								
NVDD1	P3	N1	A4	O									
NVDD1	R2	M3	D11	I/O	69K								

3 Electrical Characteristics

This section contains the electrical specifications and timing diagrams for the i.MXL processor.

3.1 Maximum Ratings

Table 4 provides information on maximum ratings which are those values beyond which damage to the device may occur. Functional operation should be restricted to the limits listed in Recommended Operating Range Table 5 on page 18 or the DC Characteristics table.

Table 4. Maximum Ratings

Symbol	Rating	Minimum	Maximum	Unit
NV_{DD}	DC I/O Supply Voltage	-0.3	3.3	V
QV_{DD}	DC Internal (core = 150 MHz) Supply Voltage	-0.3	1.9	V
QV_{DD}	DC Internal (core = 200 MHz) Supply Voltage	-0.3	2.0	V
AV_{DD}	DC Analog Supply Voltage	-0.3	3.3	V
$BTRFV_{DD}$	DC Bluetooth Supply Voltage	-0.3	3.3	V
VESD_HBM	ESD immunity with HBM (human body model)	–	2000	V
VESD_MM	ESD immunity with MM (machine model)	–	100	V
ILatchup	Latch-up immunity	–	200	mA
Test	Storage temperature	-55	150	°C
Pmax	Power Consumption	800[1]	1300[2]	mW

1 A typical application with 30 pads simultaneously switching assumes the GPIO toggling and instruction fetches from the ARM® core-that is, 7x GPIO, 15x Data bus, and 8x Address bus.

2 A worst-case application with 70 pads simultaneously switching assumes the GPIO toggling and instruction fetches from the ARM core-that is, 32x GPIO, 30x Data bus, 8x Address bus. These calculations are based on the core running its heaviest OS application at 200MHz, and where the whole image is running out of SDRAM. QVDD at 2.0V, NVDD and AVDD at 3.3V, therefore, 180mA is the worst measurement recorded in the factory environment, max 5mA is consumed for OSC pads, with each toggle GPIO consuming 4mA.

3.2 Recommended Operating Range

Table 5 provides the recommended operating ranges for the supply voltages and temperatures. The i.MXL processor has multiple pairs of VDD and VSS power supply and return pins. QVDD and QVSS pins are used for internal logic. All other VDD and VSS pins are for the I/O pads voltage supply, and each pair of VDD and VSS provides power to the enclosed I/O pads. This design allows different peripheral supply voltage levels in a system.

Because AVDD pins are supply voltages to the analog pads, it is recommended to isolate and noise-filter the AVDD pins from other VDD pins.

For more information about I/O pads grouping per VDD, please refer to Table 2 on page 4.

4 Functional Description and Application Information

This section provides the electrical information including and timing diagrams for the individual modules of the i.MXL.

4.1 Embedded Trace Macrocell

All registers in the ETM9 are programmed through a JTAG interface. The interface is an extension of the ARM920T processor's TAP controller, and is assigned scan chain 6. The scan chain consists of a 40-bit shift register comprised of the following:

- 32-bit data field
- 7-bit address field
- A read/write bit

The data to be written is scanned into the 32-bit data field, the address of the register into the 7-bit address field, and a 1 into the read/write bit.

A register is read by scanning its address into the address field and a 0 into the read/write bit. The 32-bit data field is ignored. A read or a write takes place when the TAP controller enters the UPDATE-DR state. The timing diagram for the ETM9 is shown in Figure 2. See Table 9 for the ETM9 timing parameters used in Figure 2.

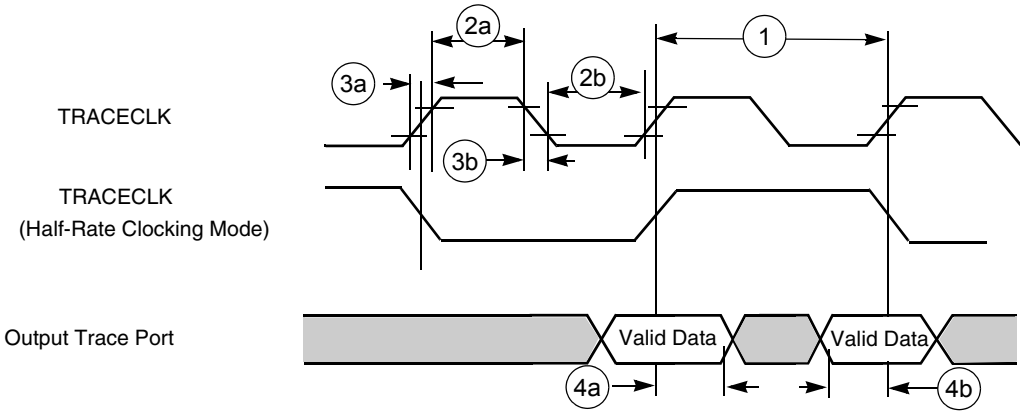


Figure 2. Trace Port Timing Diagram

Table 9. Trace Port Timing Diagram Parameter Table

Ref No.	Parameter	1.8 ± 0.1 V		3.0 ± 0.3 V		Unit
		Minimum	Maximum	Minimum	Maximum	
1	CLK frequency	0	85	0	100	MHz
2a	Clock high time	1.3	–	2	–	ns
2b	Clock low time	3	–	2	–	ns
3a	Clock rise time	–	4	–	3	ns
3b	Clock fall time	–	3	–	3	ns

4.3 Reset Module

The timing relationships of the Reset module with the POR and RESET_IN are shown in Figure 3 and Figure 4.

NOTE

Be aware that NVDD must ramp up to at least 1.8V before QVDD is powered up to prevent forward biasing.

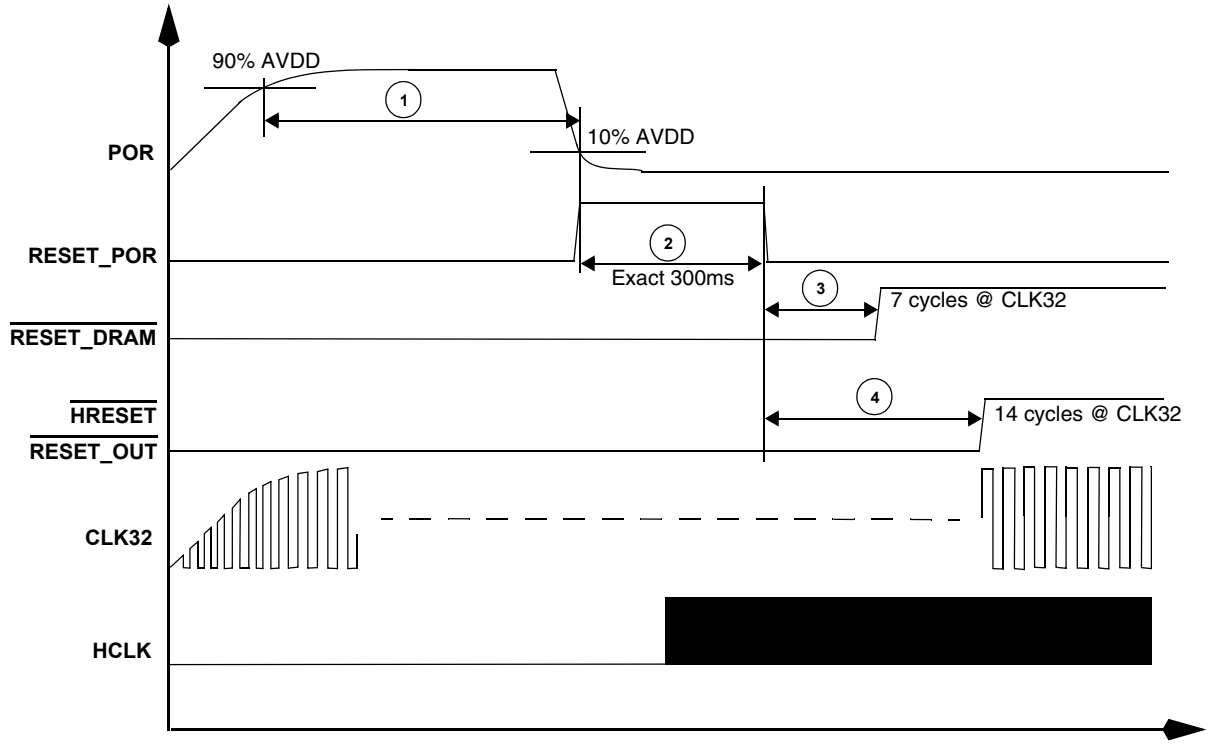


Figure 3. Timing Relationship with POR

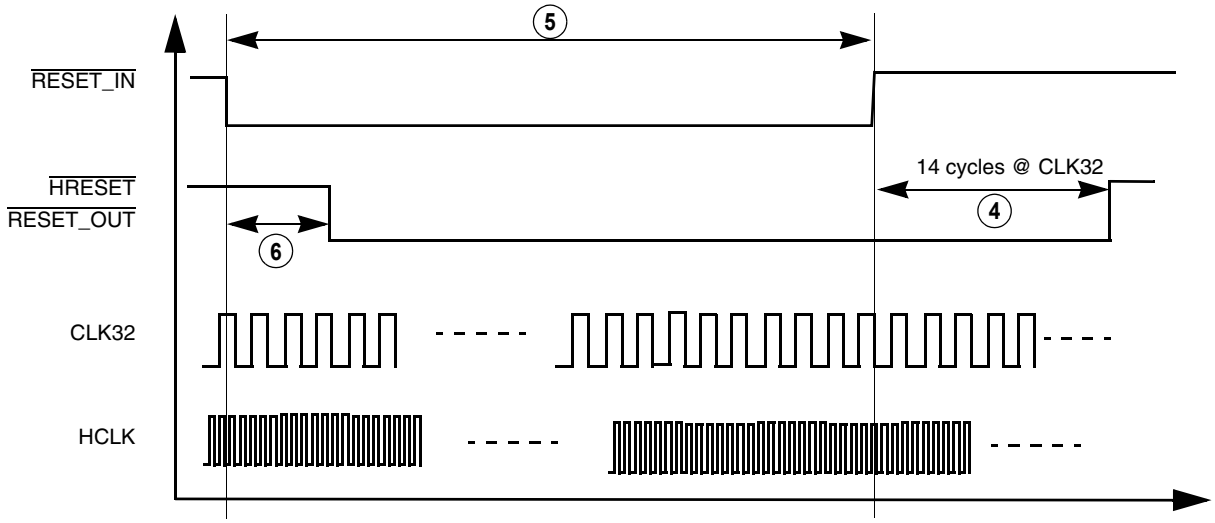


Figure 4. Timing Relationship with RESET_IN

Table 14. DTACK WAIT Read Cycle DMA Enabled: WSC = 111111, DTACK_SEL=1, HCLK=96MHz (Continued)

Number	Characteristic	3.0 ± 0.3 V		Unit
		Minimum	Maximum	
12	Wait pulse width	1T	1020T	ns

Note:
1. T is the system clock period. (For 96 MHz system clock, T=10.42 ns)
2. $\overline{OE}$ and $\overline{EB}$ assertion time is programmable by OEA bit in CS5L register. $\overline{EB}$ assertion in read cycle will occur only when EBC bit in CS5L register is clear.
3. Address becomes valid and $\overline{CS}$ asserts at the start of read access cycle.
4. The external wait input requirement is eliminated when $\overline{CS5}$ is programmed to use internal wait state.

4.4.2.3 WAIT Write Cycle without DMA

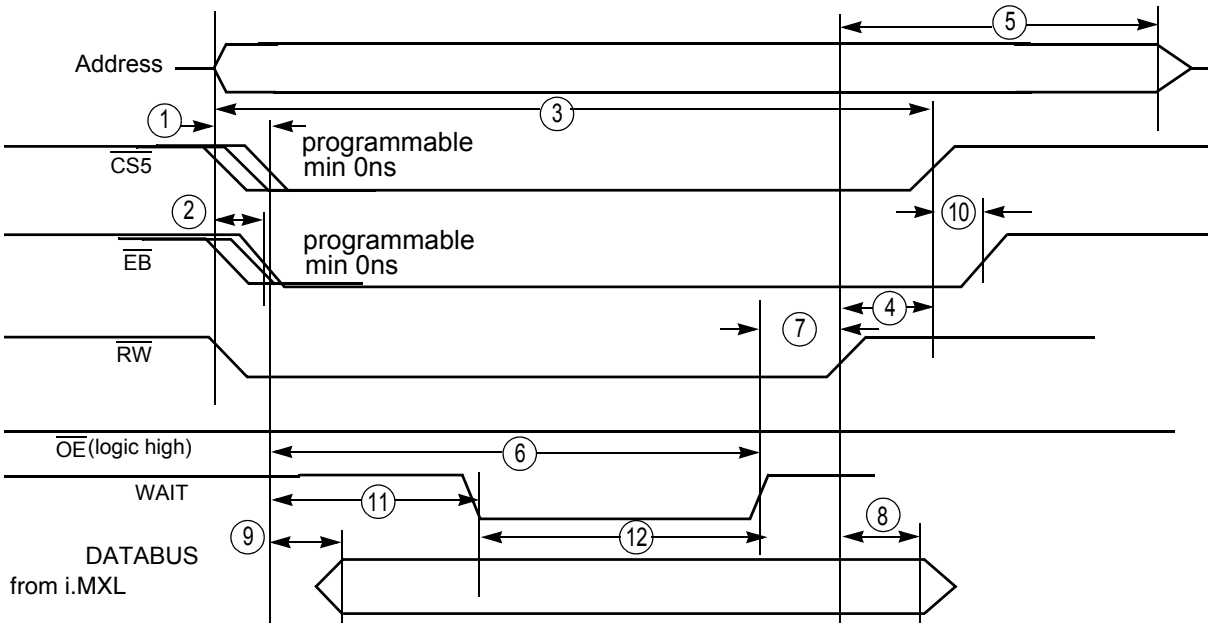


Figure 8. WAIT Write Cycle without DMA

Table 15. WAIT Write Cycle without DMA: WSC = 111111, DTACK_SEL=1, HCLK=96MHz

Number	Characteristic	3.0 ± 0.3 V		Unit
		Minimum	Maximum	
1	$\overline{CS5}$ assertion time	See note 2	–	ns
2	$\overline{EB}$ assertion time	See note 2	–	ns
3	$\overline{CS5}$ pulse width	3T	–	ns
4	$\overline{RW}$ negated before $\overline{CS5}$ is negated	2.5T-3.63	2.5T-1.16	ns
5	$\overline{RW}$ negated to Address inactive	64.22	–	ns
6	Wait asserted after $\overline{CS5}$ asserted	–	1020T	ns

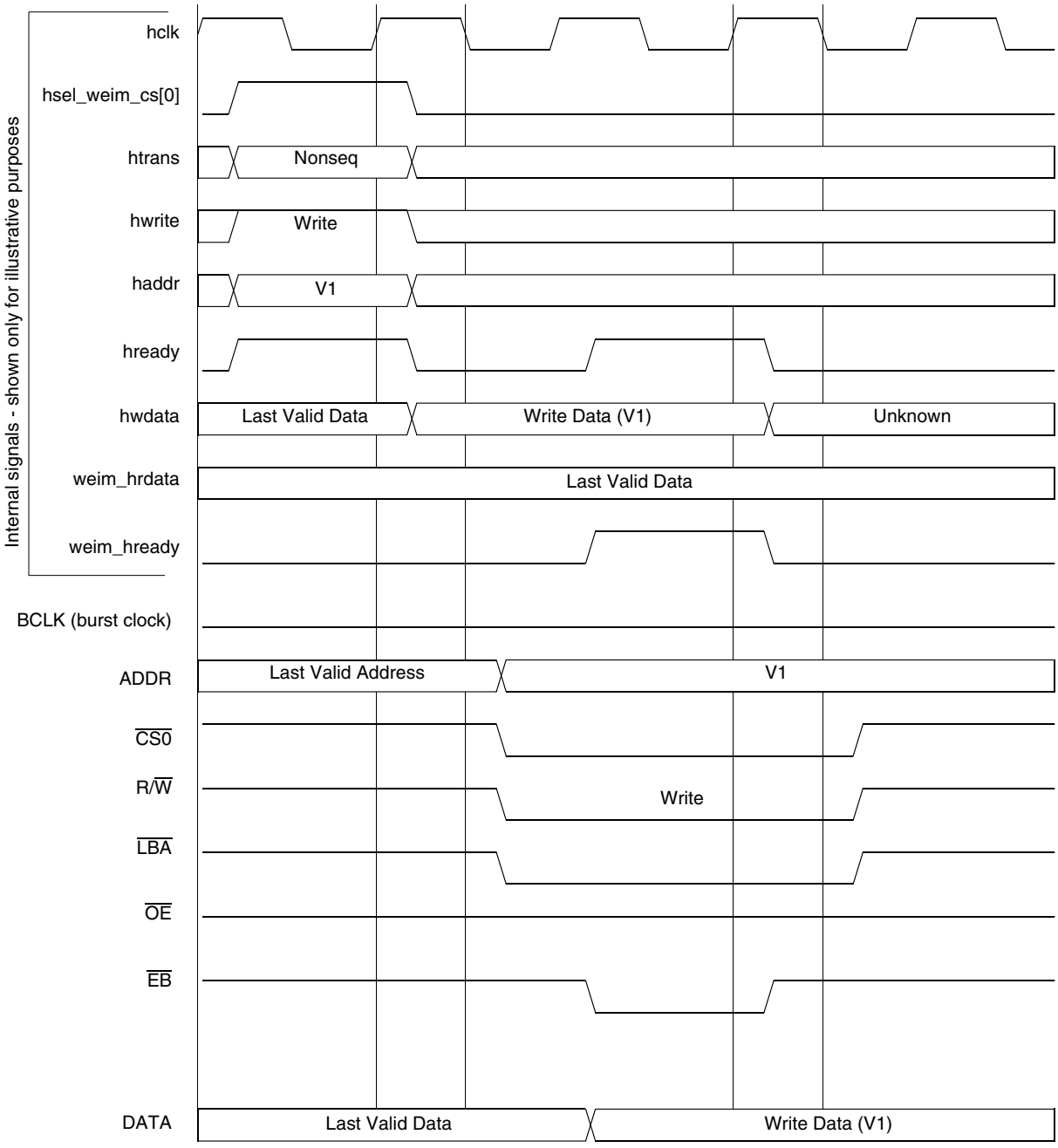
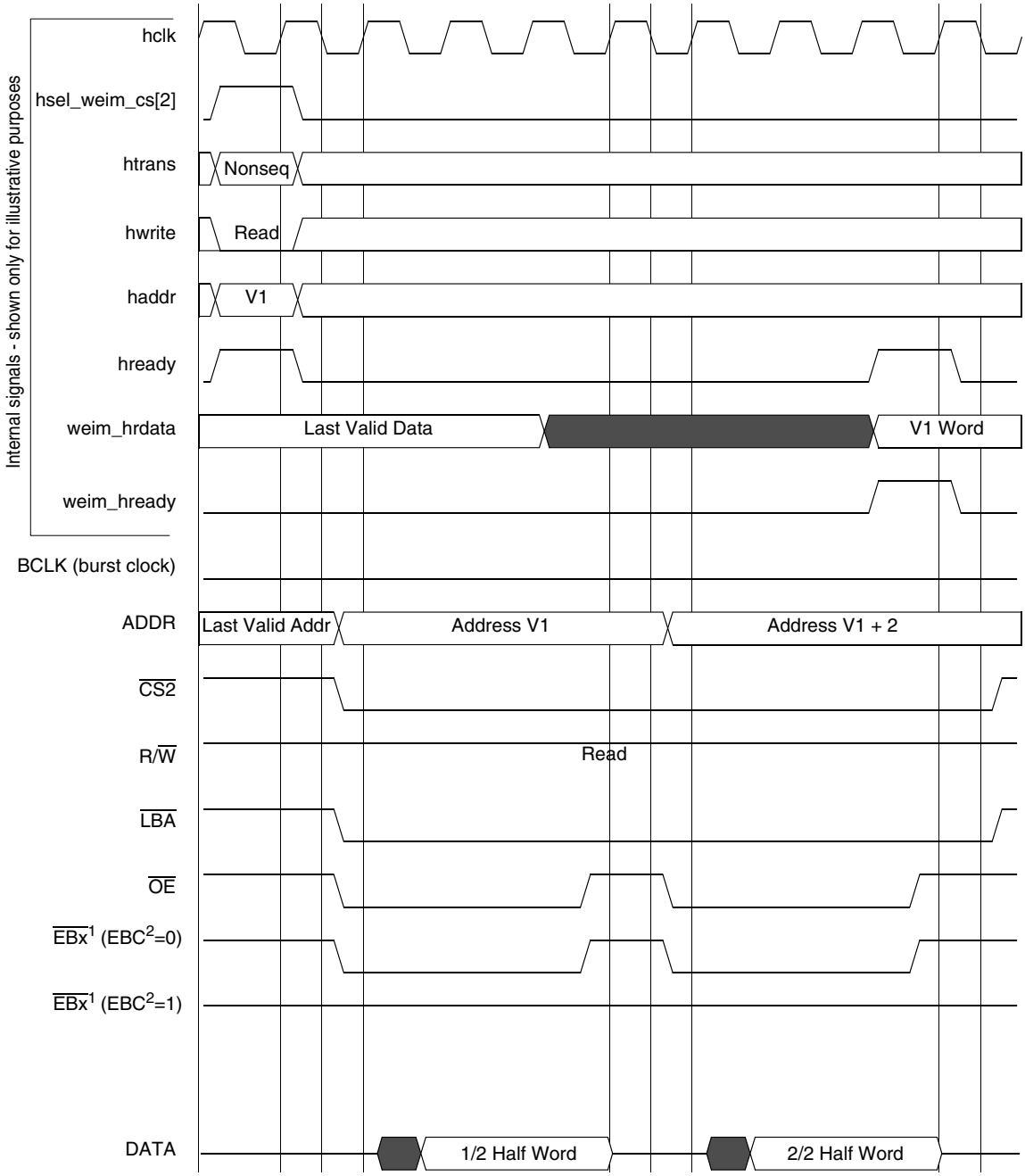
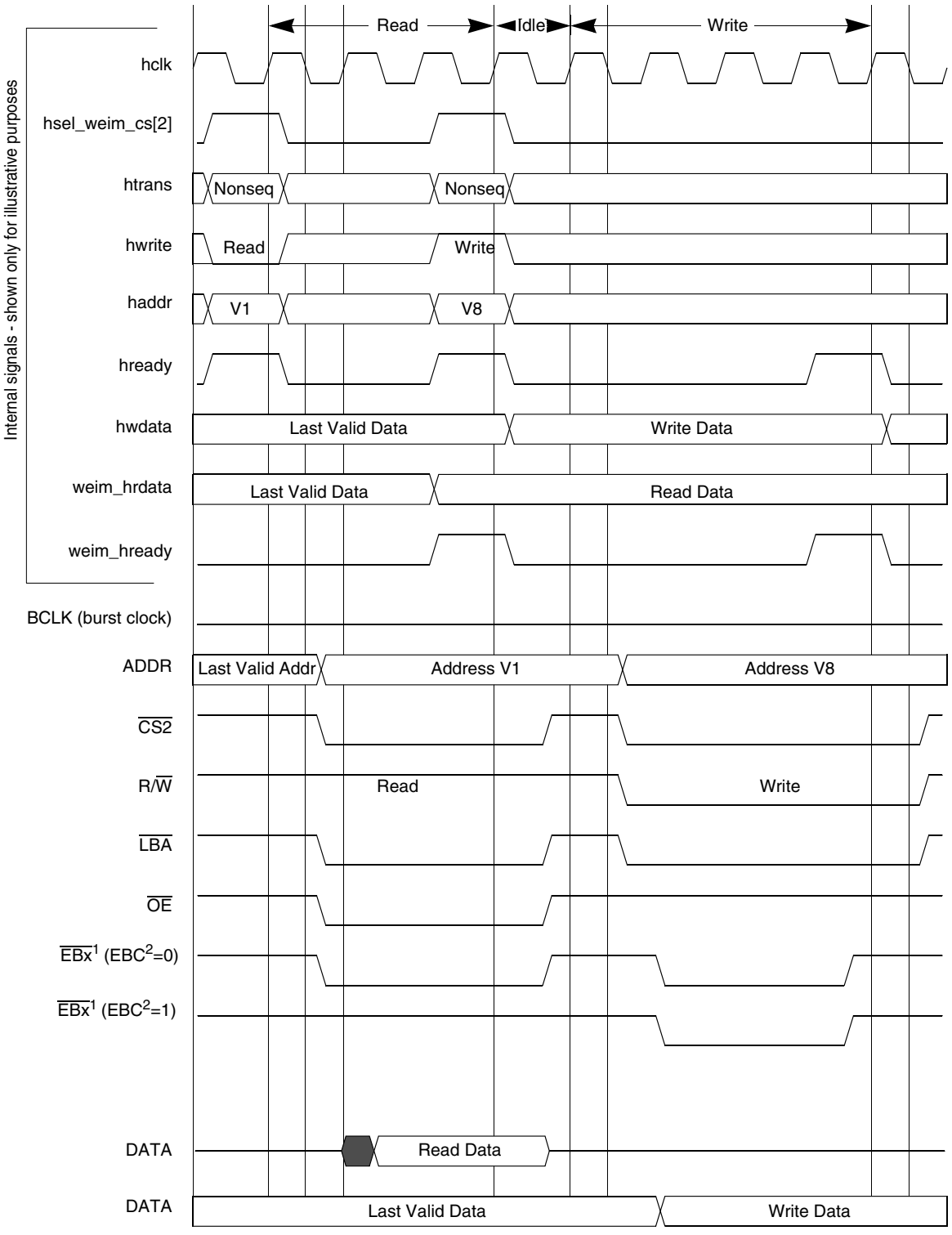


Figure 11. WSC = 1, WEA = 1, WEN = 1, A.HALF/E.HALF



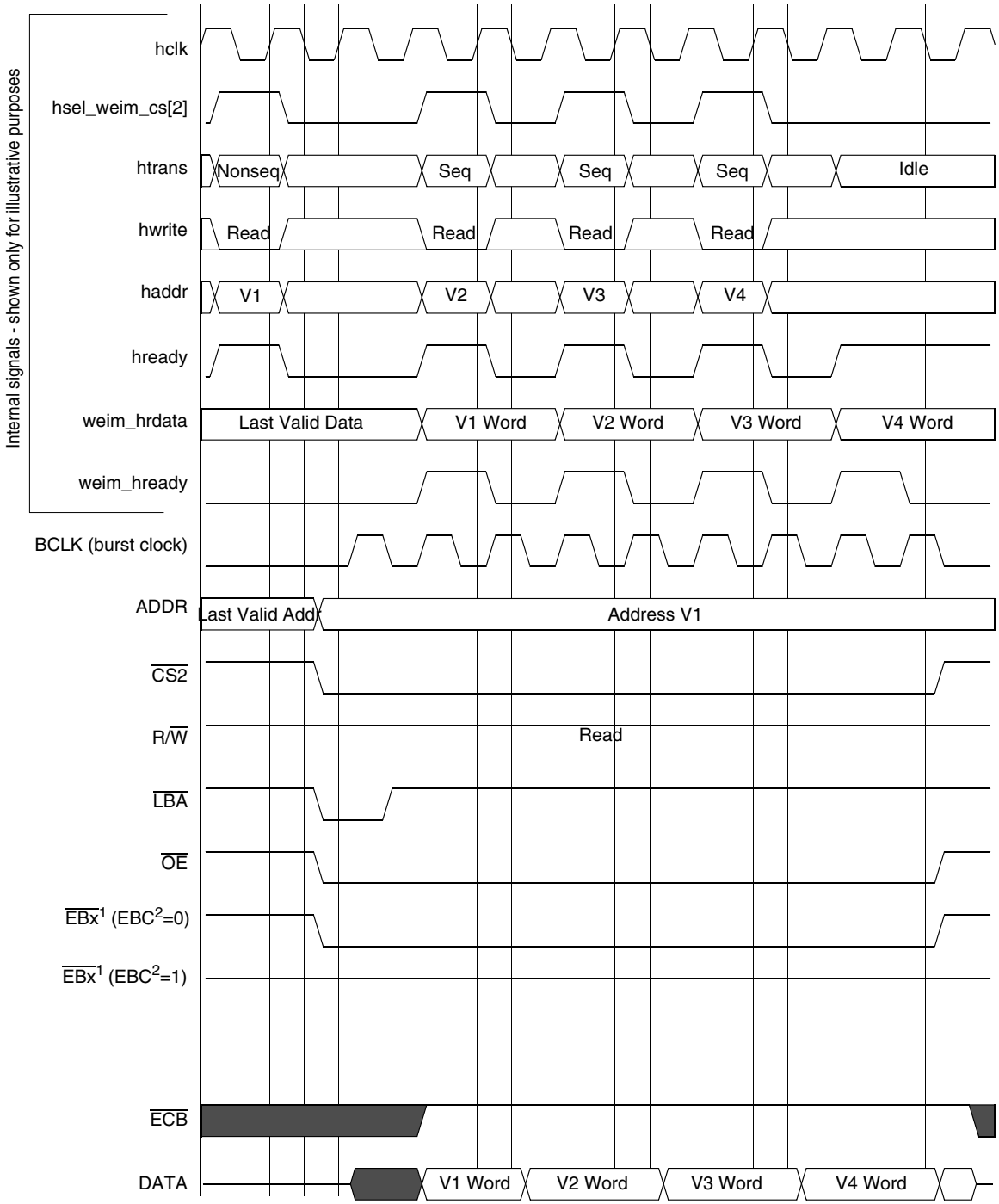
Note 1: x = 0, 1, 2 or 3
Note 2: EBC = Enable Byte Control bit (bit 11) on the Chip Select Control Register

Figure 18. WSC = 3, OEN = 2, A.WORD/E.HALF



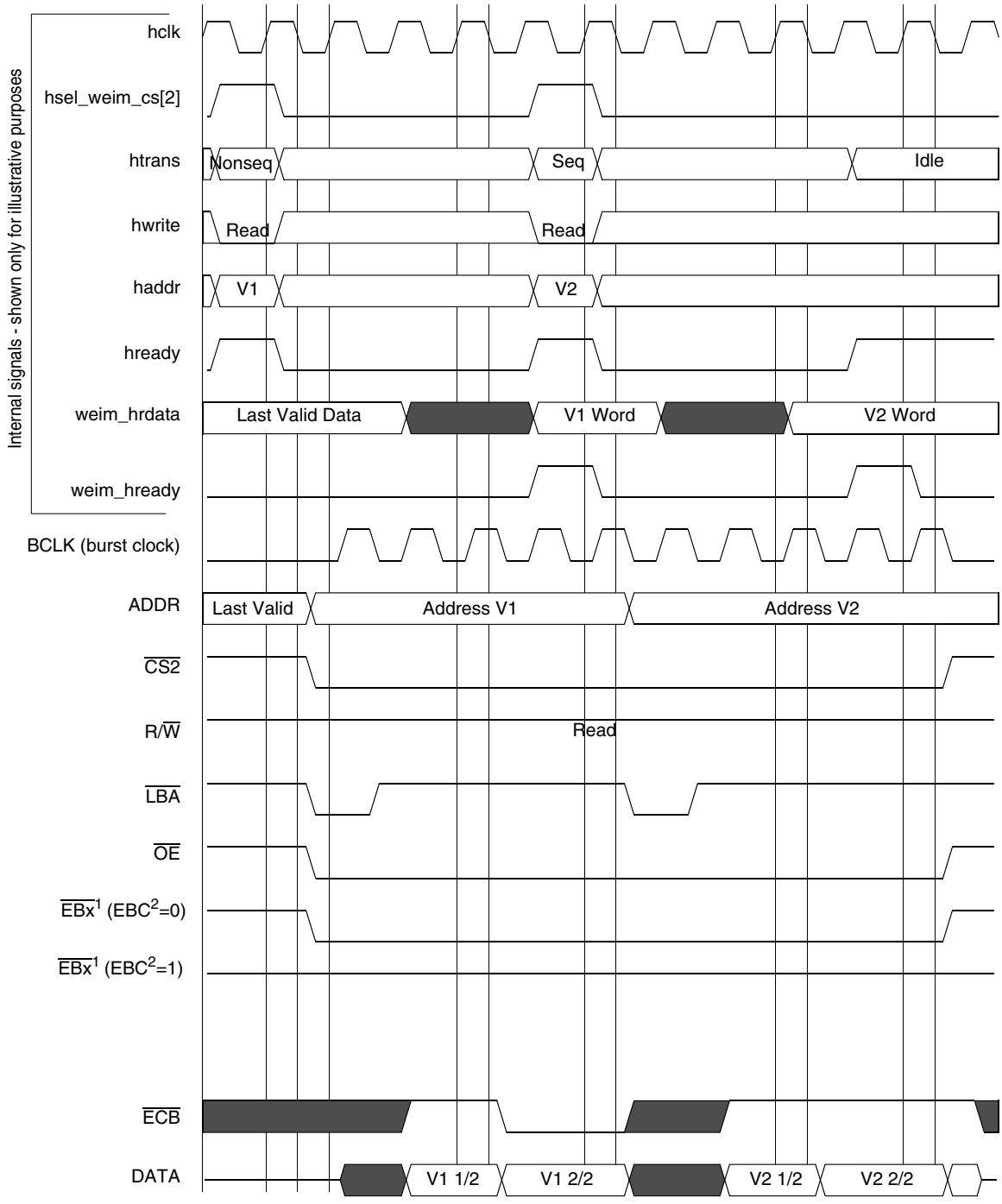
Note 1: x = 0, 1, 2 or 3
Note 2: EBC = Enable Byte Control bit (bit 11) on the Chip Select Control Register

Figure 23. WSC = 2, WWS = 1, WEA = 1, WEN = 2, EDC = 1, A.HALF/E.HALF



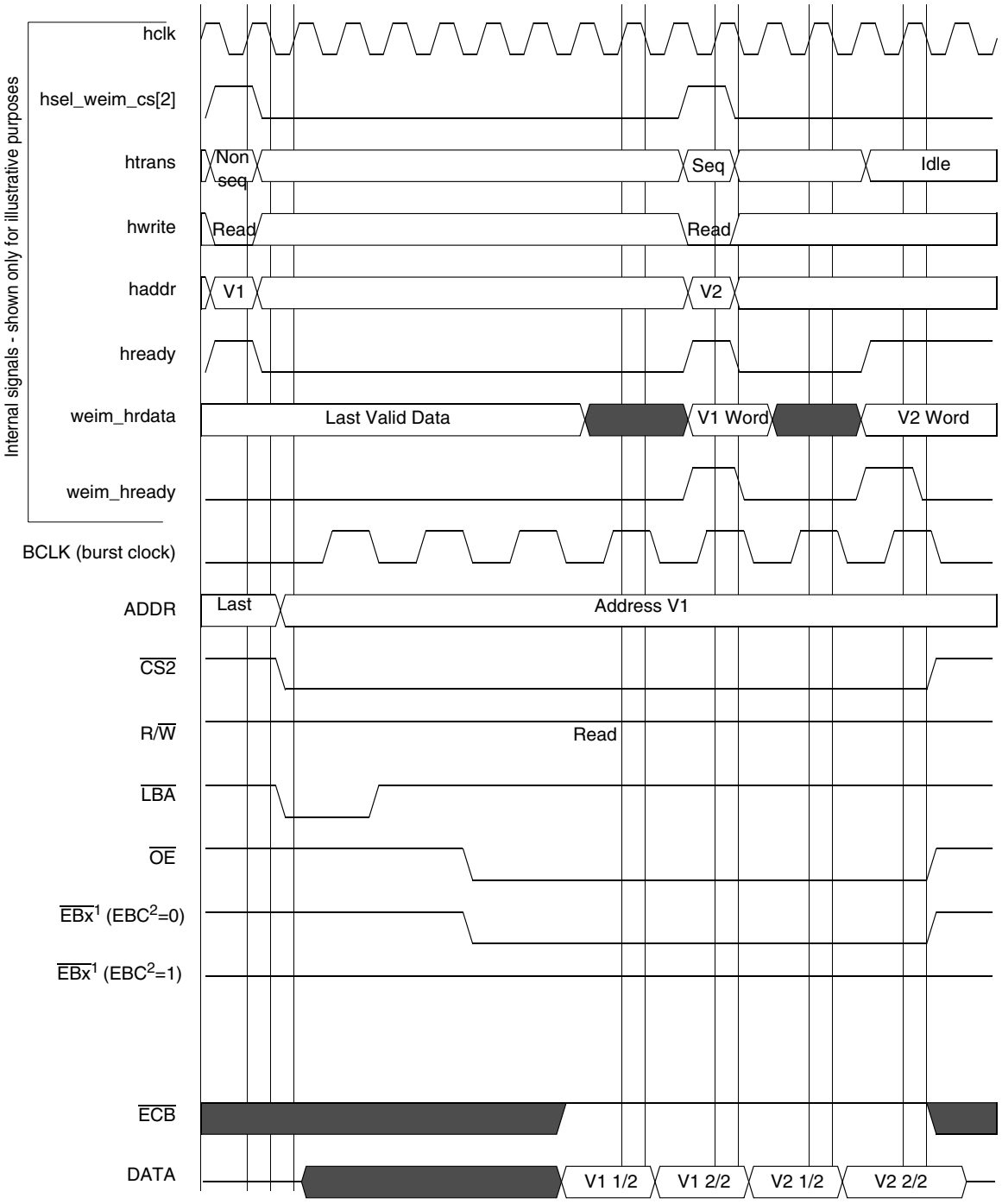
Note 1: x = 0, 1, 2 or 3
Note 2: EBC = Enable Byte Control bit (bit 11) on the Chip Select Control Register

Figure 29. WSC = 2, SYNC = 1, DOL = [1/0], A.WORD/E.WORD



Note 1: x = 0, 1, 2 or 3
Note 2: EBC = Enable Byte Control bit (bit 11) on the Chip Select Control Register

Figure 30. WSC = 2, SYNC = 1, DOL = [1/0], A.WORD/E.HALF



Note 1: x = 0, 1, 2 or 3
Note 2: EBC = Enable Byte Control bit (bit 11) on the Chip Select Control Register

Figure 32. WSC = 7, OEA = 8, SYNC = 1, DOL = 1, BCD = 1, BCS = 1, A.WORD/E.HALF

4.4.4 Non-TFT Panel Timing

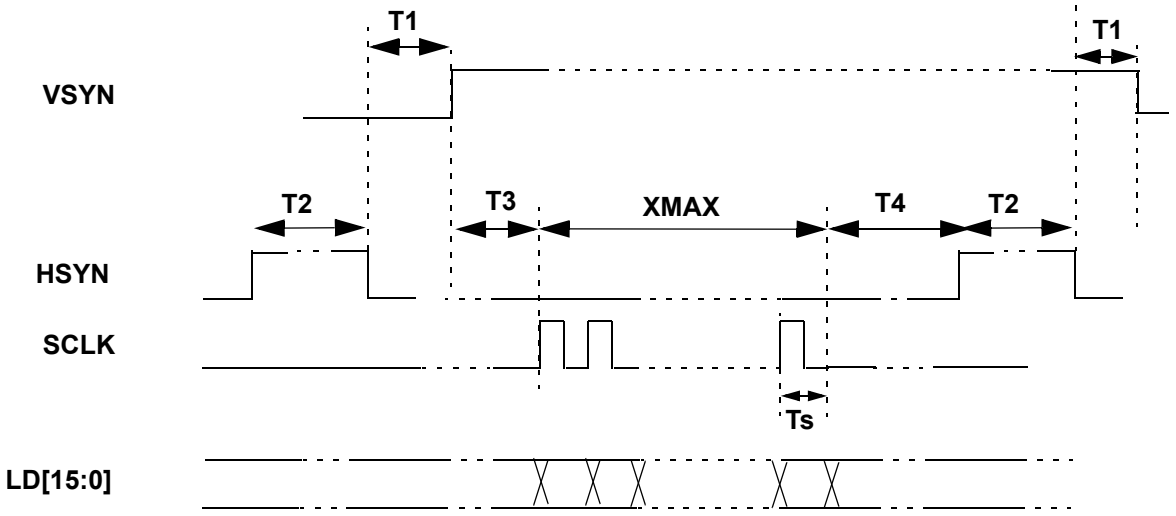


Figure 33. Non-TFT Panel Timing

Table 17. Non TFT Panel Timing Diagram

Symbol	Parameter	Allowed Register Minimum Value[1, 2]	Actual Value	Unit
T1	HSYN to VSYN delay[3]	0	HWAIT2+2	Tpix[4]
T2	HSYN pulse width	0	HWIDTH+1	Tpix
T3	VSYN to SCLK	–	0 ≤ T3 ≤ Ts[5]	–
T4	SCLK to HSYN	0	HWAIT1+1	Tpix

1 Maximum frequency of LCDC_CLK is 48 MHz, which is controlled by Peripheral Clock Divider Register.

2 Maximum frequency of SCLK is HCLK / 5, otherwise LD output will be wrong.

3 VSYN, HSYN and SCLK can be programmed as active high or active low. In the above timing diagram, all these 3 signals are active high.

4 Tpix is the pixel clock period which equals LCDC_CLK period * (PCD + 1).

5 Ts is the shift clock period. Ts = Tpix * (panel data bus width).

4.5 SPI Timing Diagrams

To use the internal transmit (TX) and receive (RX) data FIFOs when the SPI 1 module is configured as a master, two control signals are used for data transfer rate control: the $\overline{SS}$ signal (output) and the $\overline{SPI\_RDY}$ signal (input). The SPI1 Sample Period Control Register (PERIODREG1) and the SPI2 Sample Period Control Register (PERIODREG2) can also be programmed to a fixed data transfer rate for either SPI 1 or SPI 2. When the SPI 1 module is configured as a slave, the user can configure the SPI1 Control Register (CONTROLREG1) to match the external SPI master's timing. In this configuration, $\overline{SS}$ becomes an input signal, and is used to latch data into or load data out to the internal data shift registers, as well as to increment the data FIFO. Figure 34 through Figure 38 show the timing relationship of the master SPI using different triggering mechanisms.

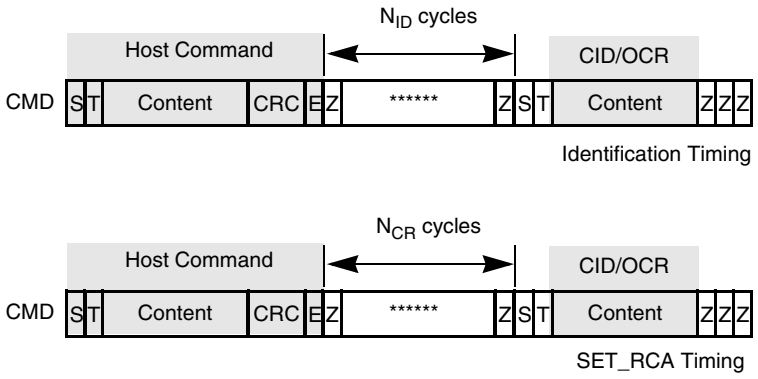


Figure 43. Timing Diagrams at Identification Mode

After a card receives its RCA, it switches to data transfer mode. As shown on the first diagram in Figure 44, SD_CMD lines in this mode are driven with push-pull drivers. The command is followed by a period of two Z bits (allowing time for direction switching on the bus) and then by P bits pushed up by the responding card. The other two diagrams show the separating periods N_{RC} and N_{CC}.

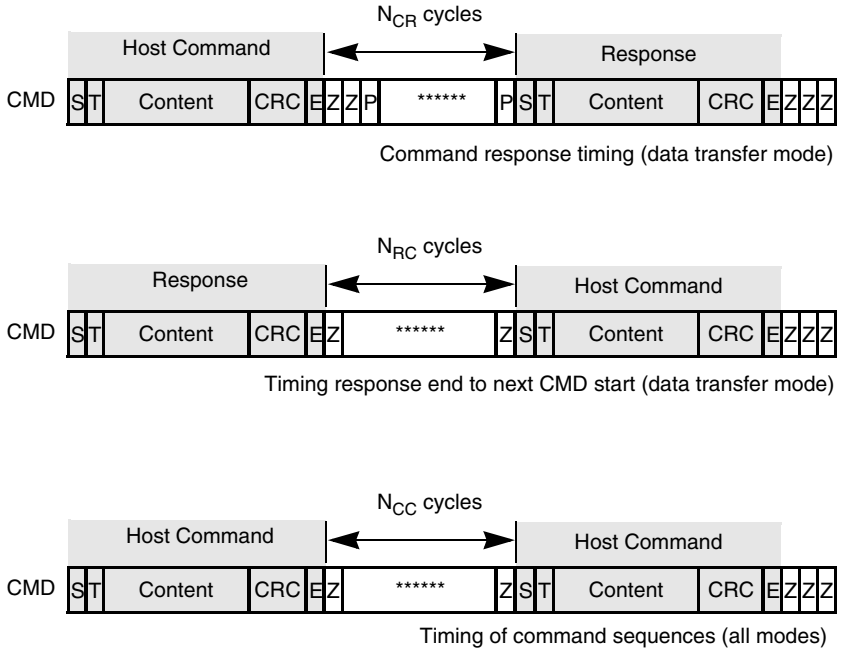


Figure 44. Timing Diagrams at Data Transfer Mode

Figure 45 shows basic read operation timing. In a read operation, the sequence starts with a single block read command (which specifies the start address in the argument field). The response is sent on the SD_CMD lines as usual. Data transmission from the card starts after the access time delay N_{AC}, beginning from the last bit of the read command. If the system is in multiple block read mode, the card sends a continuous flow of data blocks with distance N_{AC} until the card sees a stop transmission command. The data stops two clock cycles after the end bit of the stop command.

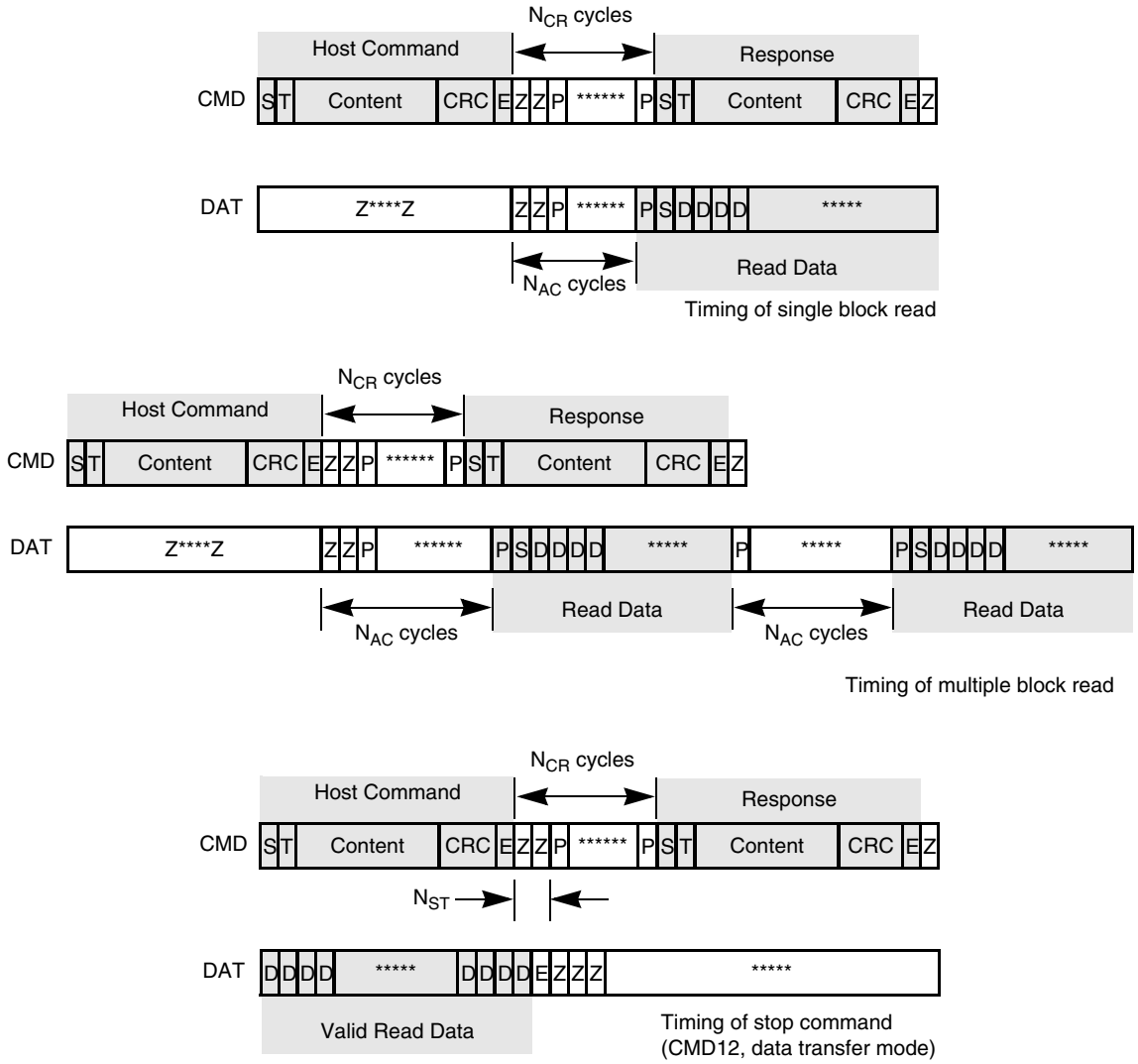


Figure 45. Timing Diagrams at Data Read

Figure 46 shows the basic write operation timing. As with the read operation, after the card response, the data transfer starts after N_{WR} cycles. The data is suffixed with CRC check bits to allow the card to check for transmission errors. The card sends back the CRC check result as a CC status token on the data line. If there was a transmission error, the card sends a negative CRC status (101); otherwise, a positive CRC status (010) is returned. The card expects a continuous flow of data blocks if it is configured to multiple block mode, with the flow terminated by a stop transmission command.

Table 25. MSHC Signal Timing Parameter Table (Continued)

Ref No.	Parameter	3.0 ± 0.3 V		Unit
		Minimum	Maximum	
12	MS_SDIO output delay time[1,2]	–	3	ns
13	MS_SDIO input setup time for MS_SCLKO rising edge (RED bit = 0)[3]	18	–	ns
14	MS_SDIO input hold time for MS_SCLKO rising edge (RED bit = 0)[3]	0	–	ns
15	MS_SDIO input setup time for MS_SCLKO falling edge (RED bit = 1)[4]	23	–	ns
16	MS_SDIO input hold time for MS_SCLKO falling edge (RED bit = 1)[4]	0	–	ns

1 Loading capacitor condition is less than or equal to 30pF.

2 An external resistor (100 ~ 200 ohm) should be inserted in series to provide current control on the MS_SDIO pin, because of a possibility of signal conflict between the MS_SDIO pin and Memory Stick SDIO pin when the pin direction changes.

3 If the MSC2[RED] bit = 0, MSHC samples MS_SDIO input data at MS_SCLKO rising edge.

4 If the MSC2[RED] bit = 1, MSHC samples MS_SDIO input data at MS_SCLKO falling edge.

4.9 Pulse-Width Modulator

The PWM can be programmed to select one of two clock signals as its source frequency. The selected clock signal is passed through a divider and a prescaler before being input to the counter. The output is available at the pulse-width modulator output (PWMO) external pin. Its timing diagram is shown in Figure 51 and the parameters are listed in Table 26.

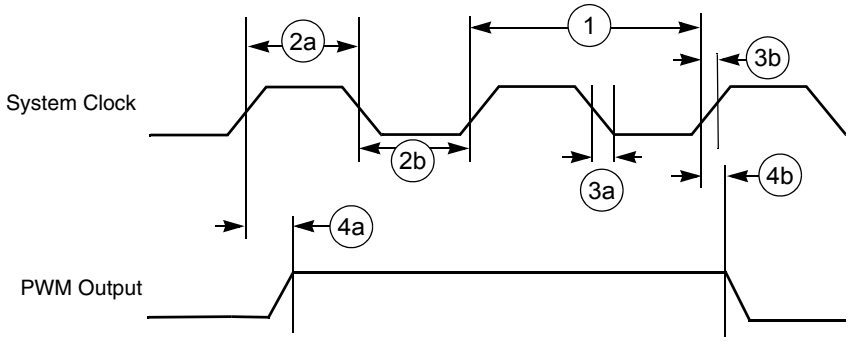


Figure 51. PWM Output Timing Diagram

Table 26. PWM Output Timing Parameter Table

Ref No.	Parameter	1.8 ± 0.1 V		3.0 ± 0.3 V		Unit
		Minimum	Maximum	Minimum	Maximum	
1	System CLK frequency[1]	0	87	0	100	MHz
2a	Clock high time[1]	3.3	–	5/10	–	ns
2b	Clock low time[1]	7.5	–	5/10	–	ns
3a	Clock fall time[1]	–	5	–	5/10	ns

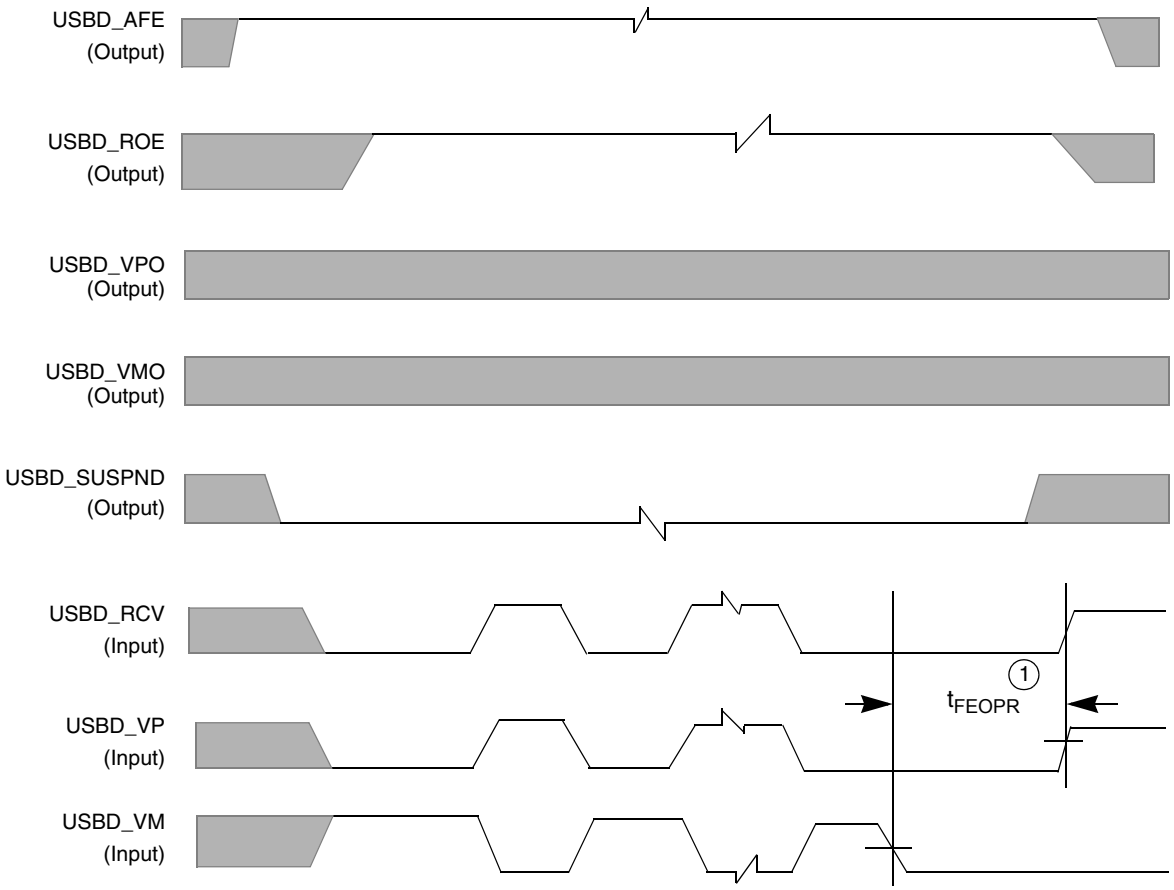


Figure 57. USB Device Timing Diagram for Data Transfer from USB Transceiver (RX)

Table 31. USB Device Timing Parameter Table for Data Transfer from USB Transceiver (RX)

Ref No.	Parameter	3.0 ± 0.3 V		Unit
		Minimum	Maximum	
1	t_{FEOPR}; Receiver SE0 interval of EOP	82	–	ns

4.12 I²C Module

The I²C communication protocol consists of seven elements: START, Data Source/Recipient, Data Direction, Slave Acknowledge, Data, Data Acknowledge, and STOP.

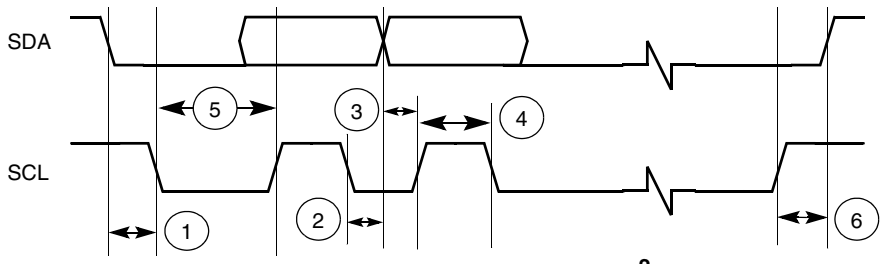


Figure 58. Definition of Bus Timing for I²C

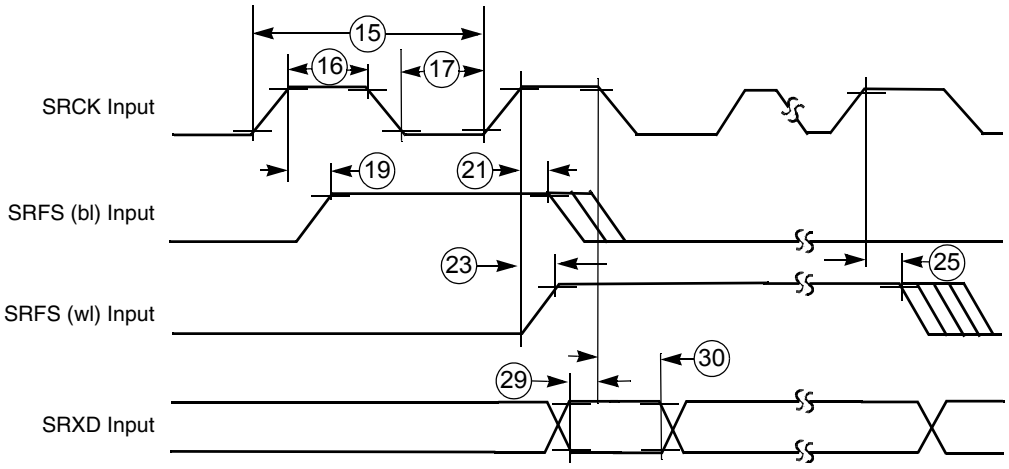


Figure 62. SSI Receiver External Clock Timing Diagram

Table 33. SSI (Port C Primary Function) Timing Parameter Table

Ref No.	Parameter	1.8 ± 0.1 V		3.0 ± 0.3 V		Unit
		Minimum	Maximum	Minimum	Maximum	
Internal Clock Operation[1] (Port C Primary Function[2])						
1	STCK/SRCK clock period[1]	95	–	83.3	–	ns
2	STCK high to STFS (bl) high[3]	1.5	4.5	1.3	3.9	ns
3	SRCK high to SRFS (bl) high[3]	-1.2	-1.7	-1.1	-1.5	ns
4	STCK high to STFS (bl) low[3]	2.5	4.3	2.2	3.8	ns
5	SRCK high to SRFS (bl) low[3]	0.1	-0.8	0.1	-0.8	ns
6	STCK high to STFS (wl) high[3]	1.48	4.45	1.3	3.9	ns
7	SRCK high to SRFS (wl) high[3]	-1.1	-1.5	-1.1	-1.5	ns
8	STCK high to STFS (wl) low[3]	2.51	4.33	2.2	3.8	ns
9	SRCK high to SRFS (wl) low[3]	0.1	-0.8	0.1	-0.8	ns
10	STCK high to STXD valid from high impedance	14.25	15.73	12.5	13.8	ns
11a	STCK high to STXD high	0.91	3.08	0.8	2.7	ns
11b	STCK high to STXD low	0.57	3.19	0.5	2.8	ns
12	STCK high to STXD high impedance	12.88	13.57	11.3	11.9	ns
13	SRXD setup time before SRCK low	21.1	–	18.5	–	ns
14	SRXD hold time after SRCK low	0	–	0	–	ns
External Clock Operation (Port C Primary Function[2])						
15	STCK/SRCK clock period[1]	92.8	–	81.4	–	ns
16	STCK/SRCK clock high period	27.1	–	40.7	–	ns
17	STCK/SRCK clock low period	61.1	–	40.7	–	ns

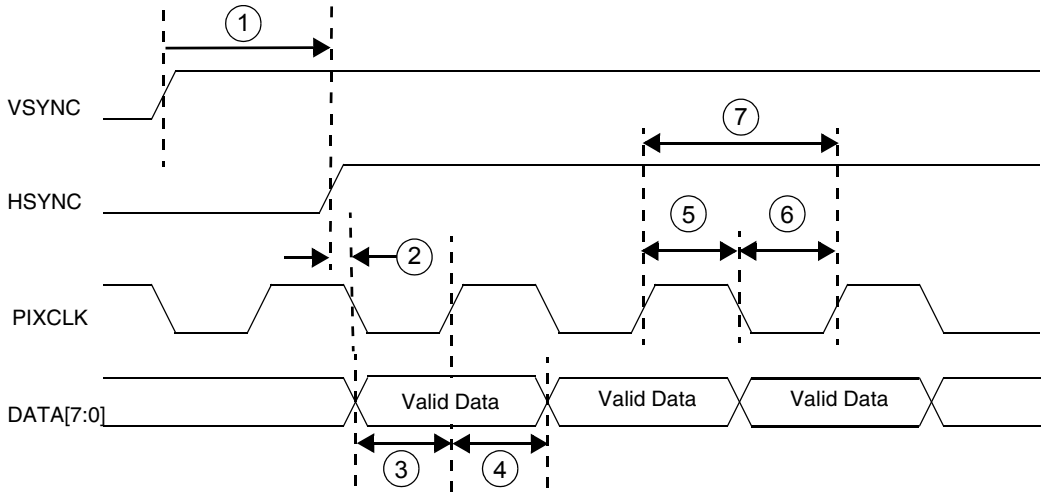


Figure 63. Sensor Output Data on Pixel Clock Falling Edge CSI Latches Data on Pixel Clock Rising Edge

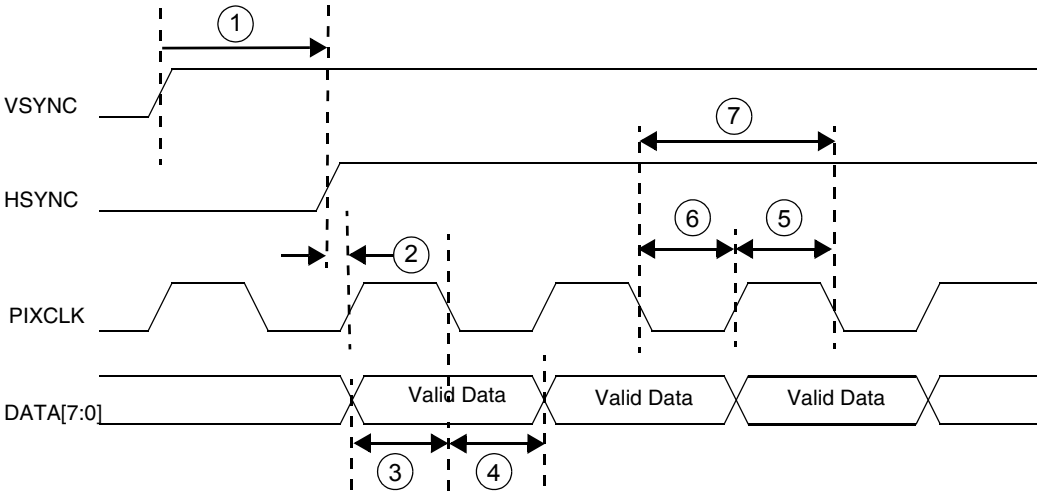


Figure 64. Sensor Output Data on Pixel Clock Rising Edge CSI Latches Data on Pixel Clock Falling Edge

Table 35. Gated Clock Mode Timing Parameters

Ref No.	Parameter	Min	Max	Unit
1	csi_vsync to csi_hsync	180	–	ns
2	csi_hsync to csi_pixclk	1	–	ns
3	csi_d setup time	1	–	ns
4	csi_d hold time	1	–	ns
5	csi_pixclk high time	10.42	–	ns
6	csi_pixclk low time	10.42	–	ns
7	csi_pixclk frequency	0	48	MHz

NOTES